

# TSM/TSP Tantalum MnO2 and KO Polymer Stacks

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## Characteristics and Typical Construction

- Variety of features by series
- Pb-Free & RoHS / ELV Compliant version standard
- 6 - 50 Volts
- 9.4 - 1980 uF Capacitance
- $\pm 10$  and 20% Capacitance tolerance
- Tray Packaging



Ref	Name	Material
A	Leadframe	BeCu Alloy 190
B	Leadframe Attach	High Temp Solder
C	Lead Termination	Solder Coated Alloy 752

## RoHS Restricted Substance Content

**Key for Determining Adherence to China RoHS and EU 2002/95/EC and 2005/618/EC Content Criteria<sup>1</sup>**  
 O =  $\leq$  MCV, X =  $>$  MCV, X =  $>$  MCV, but EU RoHS Compliant with Exemption(s)

KEMET Product	Series	Material and MCV <sup>1</sup> Termination Code	Restricted Material						Compliant Version	China RoHS Symbol <sup>2</sup>
			Cd < 0.01%	Cr <sup>6+</sup> < 0.1%	Pb < 0.1%	Hg < 0.1%	PBB < 0.1%	PBDE < 0.1%		
MnO2 Stacks	TSM	T or B	O	O	O	O	O	O	Available Since Release	
MnO2 Stacks	TSM	H or C	O	O	X	O	O	O		
Polymer Stacks	TSP	T or B	O	O	O	O	O	O	Available Since Release	
Polymer Stacks	TSP	H or C	O	O	X	O	O	O		

<sup>1</sup> MCV = Maximum Concentration Values per 2005/618/EC amending RoHS Directive 2002/95/EC and China RoHS criteria.

<sup>2</sup> China RoHS Symbol based on current manufacturing.

## Soldering Capability Characteristics

Termination Material Termination Plating (Barrier) Peak Temperature Capability Soldering Process Compatibility MSL Rating	Matte Tin Termination BeCu 100% Matte Tin (Copper, Nickel) 260°C Backward & Forward Compatible	SnPb Termination BeCu 90Sn10Pb (Copper) 260°C Backward & Forward Compatible
	MnO2 - 1/Polymer - 3	1

<sup>1</sup> Per EIA/ECA component bulletin CB19, tin whiskering is not considered a reliability risk within the capacitor industry for non-Military / Hi-Rel applications.

## Ordering

T	SM	2D	2ZT	K	086	C	H	61	20
Capacitor Class	Series	Case Size	Capacitance Code (pF)	Capacitance Tolerance	Voltage	Failure Rate/Design	Lead Material	Surge	ESR
T = Tantalum	Stacks MnO2 Cathode	2C,3C,4C,6C,2D,3D,4D,6D,2K,3K,4K,6K	First two digits represent significant figures. Third digit specifies number of zeros.	K = $\pm 10\%$ ; M = $\pm 20\%$	006 = 6.3V 010 = 10V 016 = 16V 020 = 20V 025 = 25V 035 = 35V 050 = 50V	A = 10A B = 0.15/1000 hrs C = 0.05/1000 hrs	H = Standard Solder Coated (SnPb 5% Pb minimum) C = Hot Solder Dipped E = Gold Plated T $\pm 100\%$ Tin	61 = None 82 = $\pm 10$ Cycles 25C After Vebull 83 = 10 cycles, -55C and 85C After Vebull 84 = 10 cycles, -55C and 85C Before Vebull	10 = ESR - Standard 20 = ESR - Low 30 = ESR - Ultra low

## Identification

Reel level **KEMET EZ ID** label indicates product content relative to substance restrictions of the EU RoHS Directive, 2002/95/EC, 2005/618/EC and China RoHS.  
**RoHS-PRC** = Meets criteria without exemption  
**RoHS-EU** = Meets criteria with exemption  
**RoHS-NO** = Does not meet criteria

